Product / Process Change Notification

N° 2019-032-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of additional wafer production with 8” wafer diameter for IGBT3 3300V (E3) technology and Diode EC3 3300V technology

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **30th April 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD **“JESD46“,** which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Sünner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification

N° 2019-032-A

▸ Products affected:

IGBT modules with IGBT3 3300V (E3) technology and Diode EC3 3300V technology in IHV-B housings

Please refer to attached affected product list
"pcn_2019-032-A_[*customer-no*].pdf"

▸ Detailed Change Information:

Subject:

Introduction of additional wafer production with
- 8" inch (200mm) wafer diameter for IGBT Chips and
- 8" inch (200mm) wafer diameter for Diode Chips

Reason:

Capacity extension and increasing security of supply 3300V IGBT and Diode

For IGBTs and Diodes the 8" wafer manufacturing technology is State of the Art' wafer manufacturing technology at Infineon. Therefore, these products will be shifted from 6" inch wafer diameter to 8" inch wafer diameter.

Description:

Old	New
■ **IGBT** 6 inch - chip structure with conventional edge termination - Front end Villach/ Austria	■ **IGBT** 6 inch - chip structure with conventional edge termination: - Front end Villach/ Austria 8 inch - chip structure with optimized edge termination: - Front end Villach/ Austria → Target production front end Villach/ Austria 8 inch
■ **Diode** 6 inch - chip structure with conventional edge termination: - Front end Villach/ Austria	■ **Diode** 6 inch - chip structure with conventional edge termination: - Front end Villach/ Austria 8 inch - chip structure with optimized edge termination: - Front end Villach/ Austria → Target production front end Villach/ Austria 8 inch

Product / Process Change Notification

N° 2019-032-A

▶ Product Identification:

The new modules can be identified by material number, which is part of barcode (digits 6-11) on the module label.

▶ Impact of Change:

Beside the above mentioned changes, the other specifications of the mentioned modules, like electrical- and mechanical parameters, remain unchanged according to JEDEC Standard JESD46-C: form, fit, function and reliability.

Paralleling of the modules with 6 inch and 8 inch wafer technologies is not recommended.

▶ Attachments:

- Affected product list "pcn_2019-032-A_[*customer-no*].pdf"
- Technical Information is available on request.

▶ Time Schedule:

■ Final qualification report:	On request
■ First samples available:	On request
■ Intended start of delivery:	2019-June-15 depending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.